

5 é / Descriptions

1.0A n μ É x ì ø d ý ... v k V ° MBF / x o ž
1.0A Surface Mount Glass Passivated Bridge Rectifier È MBF thin package Ä

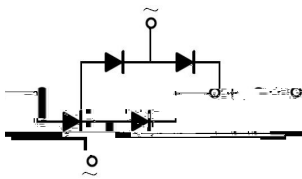
α a / Features

ì ø d ý / ì k F g 9 y < d < k 3 g v y ' k ~ ... v Ý k 9 n μ É x k —) í D
} o ž
Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current Ö1.0A, High Surge
Current Capability, Designed for Surface Mount Application, HF Product.

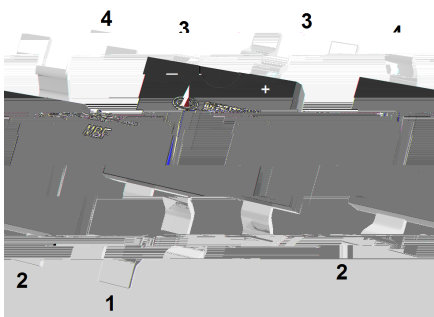
Đ ÷ / Applications

%² " (o ž
General purpose.

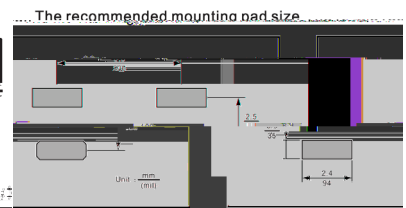
Ã W] Ô · / Equivalent Circuit



• Ô - æ / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Output Pin (+)
3	Input Pin (~)
4	Output Pin (+)



, M V / Marking

• - ~ a ¢ o ž See Marking Instructions.

1. Absolute Maximum Ratings(Ta=25℃ ;)

@ f Parameter	... Z Symbol	f > Rating						% y Unit
		MB1F-10	MB2F-10	MB4F-10	MB6F-10	MB8F-10	MB10F-10	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T _c =125 °C	I _{F(AV)}	1.0						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	35						A
Typical Junction Capacitance ^{1^A}	C _j	13						pF
Typical Thermal Resistance ^{2^A}	R _{JA}	80						/W
	R _{JC}	25						
Operating and Storage Temperature Range	T _j ,T _{stg}	-55~+150						

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4 h 1.5" h 1.5" g 3.81 h 3.81 cm h copper pad.

2. Electrical Characteristics(Ta=25℃ ;)

Parameter Symbol	Symbol	Test Conditions	Rating	Unit
Max Instantaneous Forward Voltage	V_F	$I_F=1.0A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$	5.0	A
		$T_a=125$	40	A

Electrical Characteristic Curve

Fig.1 Average Rectified Output Current
Operating Curve

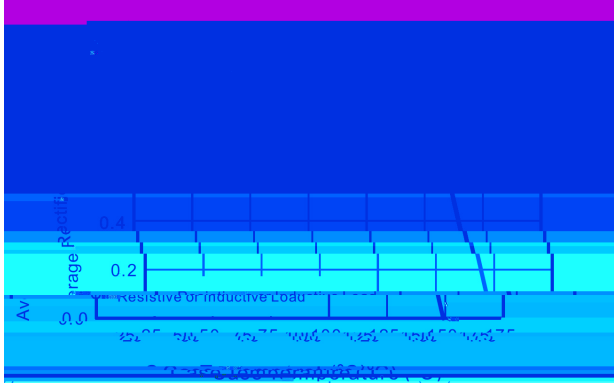


Fig.2 Typical Reverse Characteristics

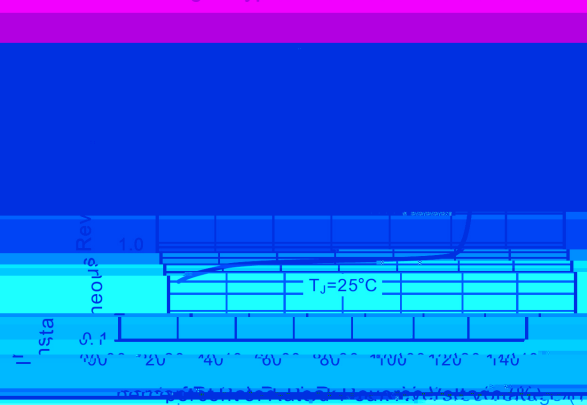


Fig.3 Typical Forward Transient Thermal Impedance

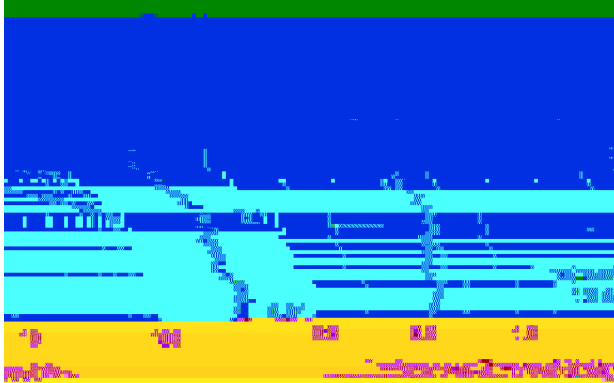


Fig.4 Typical Reverse Transient Thermal Impedance

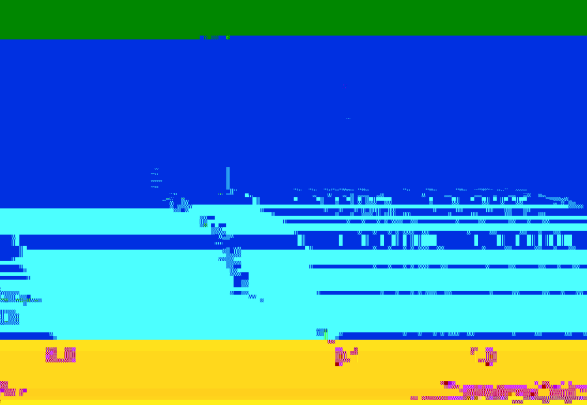
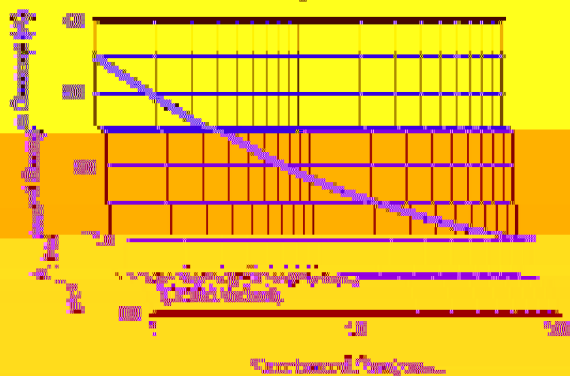
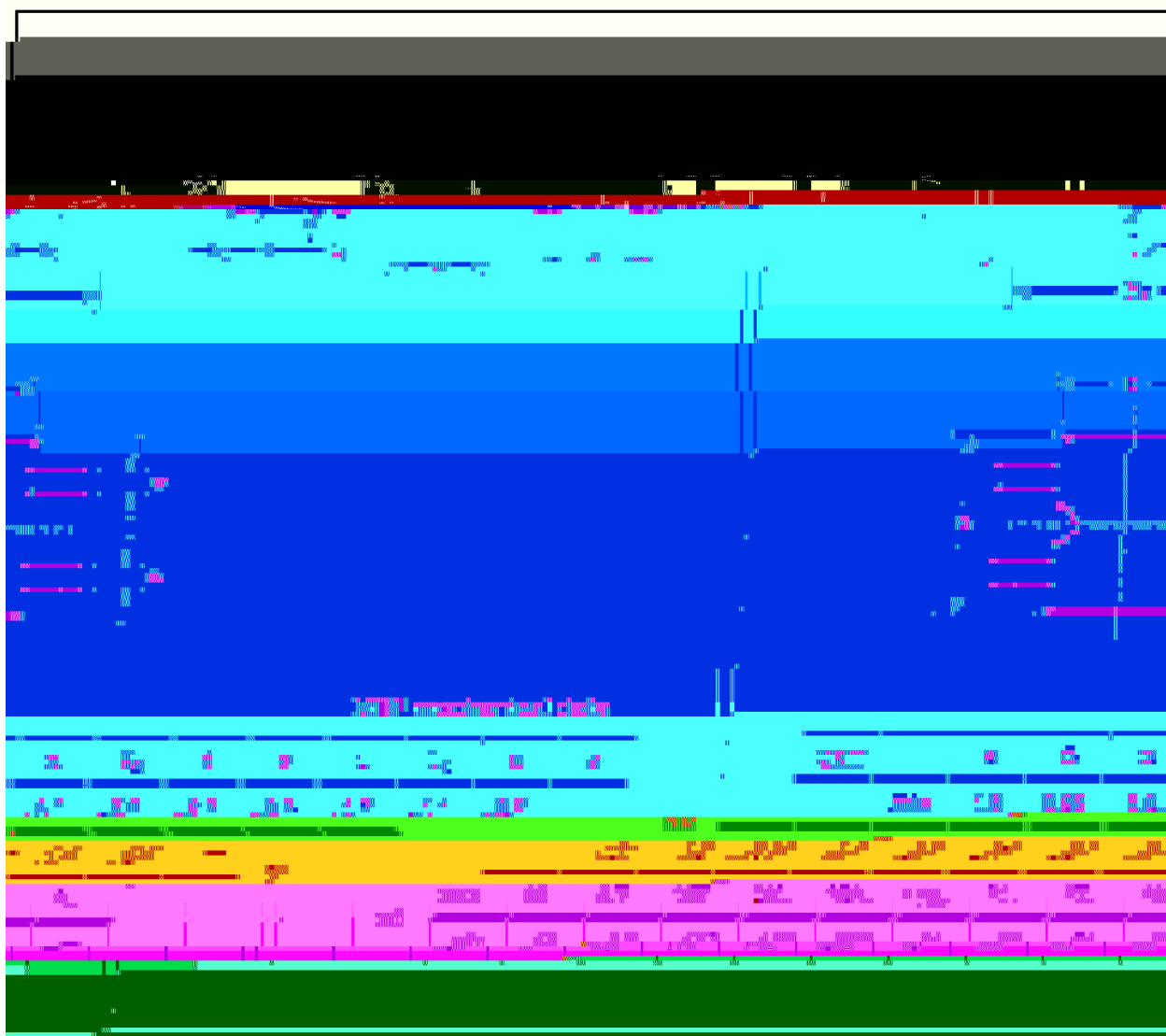


Fig.5 Maximum Non-Repetitive Peak
Forward Surge Current



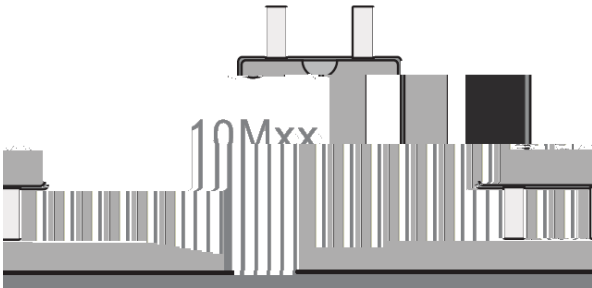
Ø □ =) ☼ / Package Dimensions

MBF

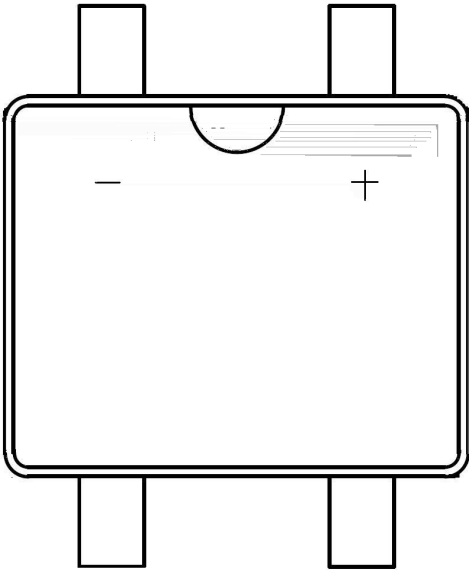


Marking

Type number	Marking code
MB1F-10	10M1
MB2F-10	10M2
MB4F-10	10M4
MB8F-10	10M8
MB8F-10	10M8
MB10F-10	10M10



, M y f / Marking Instructions



a ¢

10M1 y ° Z W A

**** y ° Z W y (* <0379>Tj /TT4.3887Tj T* ()Tj 6.555 -1.6

šWD t...•Ž¢ (x/) / :KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6

a ¢ y

- 1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;
- 2o• Q ․ “ † 245 r5 - k ž • 4 Ò 5 r0.5sec;
- 3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

- 1.Preheating:150~180 - , Time:60~90sec.
- 2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.
3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 - ž • y 10 r1 sec.

Temp.:260 r5 - Time:10 r1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ~ E	Units ;>û !H					Dimension ;>û p . (unit Åmm³)	
	Units/Reel / --	Reels/Inner Box -- /-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Reel	Inner Box